

AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph on page 11, lines 21-32 with the following amended paragraph:

In some versions of the second embodiment of the invention, the magnetic sensor may be placed on a fixed portion of a micro machined optical element. FIGS. 5A-5E depict several alternative 5 versions of this embodiment. In these versions, a magnetic structure material is characterized by a permanent magnetic moment is disposed on a moveable portion and the magnetic sensor and its associated leads are disposed on a nearby fixed portion. The magnetic material structure may produce a magnetic flux that passes through a magnetoresistive sensor, Hall effect sensor or coil 10 wherein the flux changes as the position of the magnetic material changes with respect to the sensor. Changes in flux through the sensor may cause changes an electrical property of the sensor, e.g. electrical resistance, Hall voltage or inductance. An advantage of this configuration 15 is that an electrical connection to the moveable portion is not required. This greatly simplifies the manufacture of the apparatus and improves the robustness of its operation.

Please replace the paragraph on page 12 lines 1-11 with the following amended paragraph:

15 FIG. 5A depicts a plan view of an apparatus 500 according to another alternative versions of the second embodiment of the invention. The apparatus 500 generally comprises a micro machined optical element having a fixed portion in the form of a substrate 502 and a moveable portion in the form of a flap 506. The flap is movable, e.g. rotatable with respect to an axis 503. The flap may include a light-deflecting element 507. One or more magnetic sensors 504A, 504B are 20 disposed on the substrate 502 proximate the flap 506. One or more magnetic structures elements 508A, 508B are disposed on the flap 506 near the sides thereof proximate the sensors 504A, 504B. The sensors 504A, 504B may be connected to detectors 501A, 501B through leads 505A, 505B, 505C, 505D. In the embodiment shown in FIG. 5A the sensors 504A, 504B and the magnetic structures materials 508A, 508B are oriented substantially parallel to each other and 25 substantially perpendicular to the rotation axis 503.

Please replace the paragraph on page 12, lines 12-24 with the following amended paragraph:

The magnetic structures **elements 508A, 508B** may be magnetically active materials having, e.g. a fixed magnetic moment, i.e., they may be permanent magnets. Magnetically active materials may include Nickel, Nickel-Iron, Iron-Cobalt, Aluminum-Nickel-Cobalt, Neodymium-Iron-Boron, etc., and, may be deposited in a uniform or stepped pattern. The magnetic structures **elements 508A, 508B** may alternatively include one or more coils that carry electric current to provide a magnetic moment. Each magnetic structure **element 508A, 508B** may be characterized by a magnetic moment having a direction indicated by the arrows **509A, 509B**. In the embodiment depicted in FIG. **5B** the magnetic moments of the magnetic structures **elements 508A, 508B** are oriented substantially perpendicular to the axis **503**. As the flap **506** rotates about the axis **503** the change in the relative position and/or orientation of the magnetic field produced by the magnetic structures **elements 508A, 508B** with respect to the sensors **504A, 504B** causes a change in the magnetic flux passing through the sensors **504A, 504B**. The change in flux causes a change in an electrical property of one or more of the sensors **504A, 504B**.

Please replace the paragraph beginning on page 12 line 25 and ending on page 13, line 2 with the following amended paragraph:

In a preferred embodiment, the sensors **504A, 504B** may have a C-shape that includes a gap. The sensors **504A, 505B** “wrap around” the magnetic elements **508A, 508B**. As the position of the flap **506** changes with respect to the substrate **502** the amount of magnetic flux produced by the magnetic structures **elements 508A, 508B** that is intercepted by the sensors **504A, 504B** changes. Where the sensors **504A, 504B** are magnetoresistive sensors, the change in intercepted flux produces a change in one or more sense signals detected at the detectors **501A, 501B**. In the particular version of the second embodiment shown in FIG. **5A**, the magnetic flux is a maximum when the flap **506** is substantially parallel to the substrate **502**. In this configuration, the magnetic structures **elements 508A, 508B** are disposed within the gaps in the sensors **504 A, 504B**.

Please replace the paragraph on page 13, lines 3-16, with the following amended paragraph:

FIG. 5B depicts a plan view of an apparatus 510 according to another alternative version of the second embodiment of the invention. The apparatus 510 is a variation on the apparatus 500 of FIG. 5A. The apparatus 500 generally comprises a micro machined optical element having a fixed portion in the form of a substrate 512 and a moveable portion in the form of a flap 516. A light-deflecting element 517 may be disposed on the flap 516. The flap 516 is movable, e.g. rotatable with respect to an axis 513. A magnetic sensor 514 may be disposed on the substrate 512 proximate an end of the flap 516. A magnetic structure element 518 may be disposed on the flap 516 proximate the sensor 514. The magnetic moment of the magnetic structure element 518 may be oriented substantially parallel to the axis 513, as indicated by the arrow 519. As in FIG. 5A the magnetic sensor 514 may be in the form of a magnetoresistive element having a C-shape with a gap. In the particular version of the second embodiment shown in FIG. 5A the magnetic element lies within the gap when the flap 516 is substantially parallel to the substrate 512. The magnetic sensor 514 may be coupled to a detector 511, e.g., by leads 515A, 15 515B.

Please replace the paragraph on page 14, lines 12-22 with the following amended paragraph:

One or more magnetic sensors 524 may be disposed on the top chip 525 proximate the flap 526. Although FIG. 5C shows the sensor 524 disposed on a surface of the top chip 525, a sensor 524' may alternatively be disposed on the sidewall 527. The sensors 524, 524' may be coupled to a detector 521, e.g., via leads 529A, 529B. A magnetic structure element 528[[.]], such as a magnetic material, may be disposed on the flap 526 to provide a sense magnetic field that is detected by the sensors 524, 524'. Alternatively one or more of the sensors 524, 524' may be disposed on the flap 526 and the magnetic material may be disposed on the substrate 522, the top chip 525 or the sidewalls 527. It need be stated that the top chip associated with each micro machined optical element may also be comprised of two high-aspect-ratio deep vertical walls separated by an air gap.

Please replace the paragraph beginning on page 14, line 23 and ending on page 15, line 5 with the following amended paragraph:

Several orientations of the sensors and magnetic elements are possible. Two particular configurations are depicted in FIG. 5D and FIG. 5E. FIG. 5D depicts a plan view of an apparatus 530 according to another alternative version of the second embodiment of the invention. The apparatus 530 generally comprises a micro machined optical element having fixed portions in the form of a substrate 532 and a top chip 535. The micro machined optical element includes a moveable portion in the form of a flap 536. One or more magnetic sensors 534A, 534B are disposed on the top chip 535 proximate the flap 536. The sensors 534A, 534B 5 may be coupled to a detector 531, e.g., via leads 539A, 539B. The sensors 534A, 534B may be in the form of serpentine coils of magnetic material. The serpentine shape allows a greater length for the sensors, which increases their sensitivity to changes in magnetic flux. One or more magnetic elements 538A, 538B are disposed on the flap 536 near the sides thereof. The magnetic elements 538A, 538B may be positioned such that they are proximate the sensors 10 534A, 534B when the flap 536 is clamped against the top chip 535. In this position, the magnetic flux through the sensors 534A, 534B from the magnetic structures elements 538A, 15 538B may be maximized.

Please replace the paragraph beginning on page 14, line 23 and ending on page 15, line 5 with the following amended paragraph:

20 FIG. 5E depicts a plan view of an apparatus 540 according to another alternative version of the second embodiment of the invention. The apparatus 540 generally comprises a micro machined optical element having fixed portions in the form of a substrate 542 and top chip 545. The micro machined optical element may include a moveable portion in the form of a flap 546. A magnetic sensor 544 may be disposed on the top chip 545 proximate the flap 546. The magnetic sensor 544 25 may be coupled to a detector 541, e.g. through leads 547A, 547B. The magnetic sensor 544 may be in the form of a serpentine pattern of magnetoresistive material having features in common with the serpentine pattern described with respect to FIG. 5D. One or more magnetic elements 548 may be disposed on the flap 546 proximate an end thereof. The magnetic structure element 548 may be positioned on the flap 546 such that it is proximate the magnetic sensor 544 30 when the flap is in an “on” position.